



Applicant: Joon-seo Son

Serial No.: 10/672,346

Att'y Docket No. 11948.12

Filing Date: September 26, 2003

For: DISCRETE PACKAGING HAVING INSULATED CERAMIC HEAT SINK

INFORMATION DISCLOSURE CITATIONS MADE BY APPLICANTU.S. Patent Documents

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME
<i>hm</i>	4,067,041	01/03/78	Hutson
	4,703,339	10/27/87	Matsuo
	5,019,893	05/28/91	Frank et al.
	5,886,400	03/23/99	Letterman, Jr. et al.
	6,404,065	06/11/02	Choi
	6,441,520	08/27/02	Grant
	6,507,108	01/14/03	Lindemann et al.

Examiner:

Signature

Date Considered:

Oct 19, 2004

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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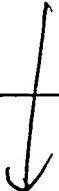

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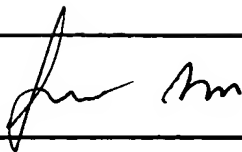
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Other Documents

EXAMINER INITIAL	DOCUMENT
	IXYS, HiPerFET™ Power MOSFETs ISPOLUS247™ (Electrically Isolated Backside), 2000, 2 pgs.
	IXYS, HiPerFET™ Power MOSFETs ISOPLUS247™ (Electircally Isolated Back Surface), 2000, 2 pgs.
	IXYS, Standard Power MOSFETs ISOPLUS247™ (Electrically Isolated Backside), 2001, 2 pgs.

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